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NYCU and University of Arizona Launch Talent and Innovation Hub to Advance Semiconductor and AI Collaboration



NYCU completed the first U.S. university agreement under its Talent and Innovation Hub (TIH) framework on January 28, marking the University of Arizona as the hub's inaugural U.S. partner.

By Chance Lai

National Yang Ming Chiao Tung University (NYCU) and the University of Arizona (UA) have formally launched

“Addressing global challenges in advanced manufacturing, artificial intelligence, and next-

the **Talent and Innovation Hub (TIH-NYCU-UA)** following the signing of a memorandum of understanding on January 28, 2026.

The agreement marks the official start of a long-term, high-impact partnership focused on talent cultivation, collaborative applied research, and industry engagement, with semiconductors and artificial intelligence identified as initial priority domains. Both universities also signaled interest in expanding collaboration into emerging technology frontiers, including space-related engineering and advanced aerospace applications.



The agreement establishing the TIH-NYCU-UA is signed by NYCU President Chi-Hung Lin (right) and University of Arizona President Suresh Garimella.

From Strategic Dialogue to Operational Platform

generation aerospace systems requires partnerships that are both international and deeply collaborative,” said Suresh Garimella, President of the University of Arizona. “NYCU is a natural partner for the University of Arizona—not only because of its leadership in semiconductors and AI, but because of its ability to translate academic excellence into real-world impact. We see strong potential to extend this collaboration into space-related technologies as the partnership evolves.”

By aligning complementary strengths, NYCU and UA aim to deliver industry-facing outcomes that connect education and research with real workforce and innovation demands in both Taiwan and the United States.

A Phased and Expandable Roadmap

Under the jointly endorsed operational framework, the Talent and Innovation Hub will progress through clearly defined phases, beginning with pilot talent programs and applied research

The Talent and Innovation Hub (TIH) is designed as a joint, scalable platform that integrates graduate-level education, professional workforce development, and application-oriented research. Rather than operating as a single fixed program, TIH adopts a phased and expandable implementation model, allowing initiatives to grow in scope and depth as institutional capacity and industry needs evolve.

“This partnership reflects NYCU’s long-term commitment to connecting education, research, and industry through concrete, executable platforms,” said Chi-Hung Lin, President of NYCU. “By working closely with the University of Arizona, we are not only cultivating next-generation talent in semiconductors and AI, but also establishing a mechanism that enables people, knowledge, and innovation to move seamlessly between Taiwan and the United States.”

The launch event was attended by Professor Jong-Shinn Wu, Director General of the Taiwan Space Agency

initiatives, and culminating in deeper institutional integration and expanded international participation.

This phased approach emphasizes flexibility, scalability, and long-term sustainability, while maintaining semiconductors and AI as foundational focus areas during the initial stages of collaboration, with pathways open for future expansion into aerospace and space technology domains.



NYCU President Chi-Hung Lin and University of Arizona President Suresh Garimella unveil the TIH-NYCU-UA, marking its official launch.

Strengthening Taiwan–U.S. Talent and Innovation Linkages

The TIH-NYCU-UA represents more than a bilateral academic agreement. It serves as a strategic mechanism to strengthen Taiwan–U.S. collaboration in advanced

(TASA) and a faculty member at NYCU, whose presence underscored Taiwan's growing ambitions in space technology and the importance of linking semiconductor and AI capabilities with future aerospace systems.

In its initial phase, TIH will prioritize graduate and professional talent training, industry-aligned reskilling programs, collaborative applied research projects, and two-way exchanges of students, faculty, and research professionals.

Leveraging Complementary Strengths in Taiwan and Arizona

As a member of the Association of American Universities (AAU), the University of Arizona brings internationally recognized strengths in engineering, materials science, photonics, semiconductor manufacturing, and applied technology innovation. UA plays a central role in Arizona's research and workforce ecosystem, particularly as the state continues to expand its

technologies, workforce development, and applied research amid growing global demand for high-skilled talent.

By aligning leadership vision, faculty-level collaboration, and industry engagement on a shared platform, NYCU and the University of Arizona aim to establish a model that is locally grounded, globally connected, and capable of generating sustained impact across semiconductors, AI, and the emerging space economy.

presence in the global semiconductor supply chain.

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Group photo at the signing ceremony



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